



Advanced Packaging (3D) R&D Program Director

About the company

QPlox Engineering is a leading technology company specializing in innovative solutions for IoT frameworks, instrumentation systems, and test automation. Our clients are major multinational enterprises and local companies from automotive, semiconductors, RF, and consumer electronics. We are committed to pushing the boundaries of technology and providing our clients with cutting-edge solutions. Our dynamic team thrives on collaboration, creativity, and continuous learning.

Job Description

We are looking for a dynamic **3D Integration Program Director** who is passionate about **research and development (R&D)** and eager to drive innovation in **telecom, network technologies, and 3D engineering**. Join us in shaping the future of cutting-edge technology!

Key Responsibilities

- **Lead high-impact projects in AI/CPU, networking, and next-gen technologies** to drive innovation.
- **Develop and implement** a cutting-edge **3D engineering architecture** tailored to advanced application scenarios.
- **Break down complex engineering structures** into actionable plans, manage risks, and transform technical concepts into **commercial successes**.
- **Conduct pioneering research** and engage in **global knowledge exchange** with industry leaders in **3D integration technologies**.
- **Leverage your expertise in 3D IC, 3D packaging, and chip-to-chip technologies** to shape the future of **telecommunications, AI, and 5G**.

Location: Leuven, Belgium

Candidate Skills and Requirement

- **PhD in Engineering, Materials Science, or a related field** – your expertise will drive innovation.
 - **10+ years of experience in 3D integration, semiconductor manufacturing, or advanced materials.**
 - Strong technical knowledge of **3D IC technologies, heterogeneous integration, MEMS, and chip stacking.**
 - **Exceptional communication skills and a collaborative mindset** to work with top industry experts.
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- **Proven leadership experience** in managing complex projects and solving critical technical challenges.
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Benefits

- Work alongside **global experts** and drive advancements in **3D integration**.
 - Competitive salary and benefits package.
 - Opportunities for professional growth and development.
 - Lead **groundbreaking projects** that will define the future of **next-gen semiconductors and telecom technologies**.
 - Collaborative and innovative work environment.
 - Flexible working hours and remote work options.
 - Plenty of learning opportunities.
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Contact

Send your CV and application letter detailing their experience and qualifications to jobs@qplox.com with the subject "**Advanced Packaging (3D) R&D Program Director**".
